3528 Torrance Blvd, Suite 100
Torrance, CA 90503
Ph: 310-540-7310
Fax: 310-540-7930
Web site: www.seikausa.com

For Immediate Release

Contact:
Seika Machinery, Inc.
310-540-7310
Email: info@seikausa.com
Web site: www.seikausa.com

Seika Machinery, Inc. to Feature Leading Machinery at APEX 2010

TORRANCE, CA — March 2010 — Seika Machinery, Inc., a leading provider of advanced machinery, materials and engineering services, will feature its leading machinery in booth 407 at the upcoming IPC/APEX conference and exhibition, scheduled to take place April 6-8, 2010 at the Mandalay Bay Resort & Convention Center in Las Vegas.

Seika's new Solder Paste Recycling Unit enables approximately 90 percent of waste solder paste to be recovered as solder bar. The system provides a major decrease in disposal costs for factory waste, a reduction in CO_2 emissions, and reduced costs for solder bar as a result of recycling waste. As an additional benefit, the recycling unit enables selection of manual mode and automatic mode using a touch screen panel.

The **Anritsu 3D Solder Paste Inspection System** features numerous advanced technology features including ultra-high resolution: horizontal (10 µm/20 µm interchangeable) and vertical (1 µm, best in class), high-speed inspection (33 sq cm/sec at 20 µm resolution; 13.8 sq cm/sec at 10 µm resolution), and easy programming and maintenance in that program generation is accomplished in approximately five minutes and consistent results are provided, regardless of the operator.

Additionally, the system offers many benefits to users such as an automatic calibration function for easy maintenance, SPC software that is included as standard for detailed analysis and traceability, and reliable and accurate zero plane reference points.

McDry Electronic Drying Storage Cases provide low-humidity storage without the use of nitrogen. Humidity is removed from the cabinets by use of a zeolite desiccant. The desiccant is automatically recycled by the unit and does not require replacement.

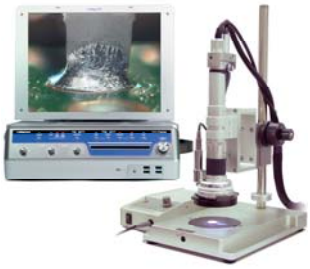
McDry units come in 1 and 3 percent RH models to comply with the strict standards required for proper storage of moisture-sensitive materials requiring ultra-low humidity levels.

3528 Torrance Blvd, Suite 100
Torrance, CA 90503
Ph: 310-540-7310
Fax: 310-540-7930
Web site: www.seikausa.com

Sawa Ultrasonic Stencil Cleaners are widely used in the Japanese electronics industry to ensure high yields when screen printing solder paste onto PCBs. Normal cloth wipe cleaning of stencils cannot completely remove solder paste especially in fine-pitch applications because a small amount of solder balls have a tendency to adhere to the corners of the apertures. Sawa Stencil Cleaners are able to completely remove solder paste using ultrasonic vibration and require no special solvents as they are effective with solvents, including water-based isopropyl alcohol.

Sayaka's CT23NJ Series is comprised of fast and accurate standalone PCB routers, with a CCD camera and sophisticated image-processing software. Sayaka Routers are the ideal solution for stress-free depanelization, providing a fixture-based highly efficient dust vacuum system. The routers provide clean and precise depanelization for densely populated PCBs, and the advanced image-processing software offers point-and-click operation for programming router paths.

HIROX 3D Digital Microscopes are dedicated digital microscopes, allowing a sample to be observed directly through a lens. The microscopes have been optimized for the characteristics of the imaging sensor — a flat, 2-D array with a known readout rate, response curve, pixel size, etc.



In a conventional microscope, the optics of the eye must be figured into the design parameters and that requirement may be different from, and potentially conflict with, those that would produce optimal images with an electronic imaging sensor. Because the HIROX microscopes have been designed only for digital imaging, no compromises have been made to accommodate the eye's optics. However, the systems are, in fact, often able to take advantage of sight physiology and visual signal processing to provide unique observational capabilities, i.e. 3-D rotational microscopy.

YJ Link's SPI NG/Good Buffer is designed to stack NG PCBs and transfer good PCBs to the next process using FIFO. Features include PCB shock-free and noncontact power transmission, RS-232C interface with SPI, and NG PCB anti-touch verification. This method provides increased line efficiency and requires only minimal space for equipment. Using the SPI NG/Good Buffer, there is no need to filter NG PCBs and SPI operates normally, even during NG PCB verification.

YJ Link's AOI NG Buffer stacks NG PCBs and pushes good PCBs to the next AOI inspection process. This system also features a PCB shock-free and noncontact power transmission.

Both systems feature a SMEMA interface, a slim, round design, adjustable stacking, a LED tower light and touch screen operation.

3528 Torrance Blvd, Suite 100
Torrance, CA 90503
Ph: 310-540-7310
Fax: 310-540-7930
Web site: www.seikausa.com

For more information, stop by booth 407 at the show or visit www.seikausa.com.

###

About Seika Machinery, Inc.
Seika Machinery, Inc. (SMI) is a subsidiary of Seika Corporation, Japan and member of the Mitsubishi Global Group. SMI provides electronics manufacturers with advanced machinery, superior materials and engineering services.